

L Number	Hits	Search Text	DB	Time stamp
-	133	((438/462).CCLS.) and laser	USPAT; US-PGPUB	2002/09/25 12:01
-	777274	cutting or cut or dice or dicing or diced	USPAT; US-PGPUB	2002/09/22 13:09
-	215990	laser	USPAT; US-PGPUB	2002/09/22 13:10
-	357	(438/462).CCLS.	USPAT; US-PGPUB	2002/09/19 10:44
-	16804	(cutting or cut or dice or dicing or diced) with laser	USPAT; US-PGPUB	2002/09/19 10:46
-	63	((438/462).CCLS.) and ((cutting or cut or dice or dicing or diced) with laser)	USPAT; US-PGPUB	2002/09/19 10:46
-	31033	(cutting or cut or dice or dicing or diced) with (substrate or wafer)	USPAT; US-PGPUB	2002/09/19 10:47
-	1543	laser with ((cutting or cut or dice or dicing or diced) with (substrate or wafer))	USPAT; US-PGPUB	2002/09/19 10:47
-	36	((438/462).CCLS.) and (laser with ((cutting or cut or dice or dicing or diced) with (substrate or wafer)))	USPAT; US-PGPUB	2002/09/19 10:59
-	51	438/463.ccls.	USPAT; US-PGPUB	2002/09/19 10:59
-	17	(laser with ((cutting or cut or dice or dicing or diced) with (substrate or wafer))) and 438/463.ccls.	USPAT; US-PGPUB	2002/09/22 13:09
-	371	438/for.386.ccls.	EPO; JPO; DERWENT	2002/09/22 13:09
-	779780	cutting or cut or dice or dicing or diced	EPO; JPO; DERWENT	2002/09/22 14:10
-	347960	laser	EPO; JPO; DERWENT	2002/09/22 13:10
-	21	438/for.386.ccls. and (cutting or cut or dice or dicing or diced) and laser	EPO; JPO; DERWENT	2002/09/22 13:10
-	4386	"pulse laser"	USPAT; US-PGPUB	2002/09/22 14:10
-	31033	(cutting or cut or dice or dicing or diced) with (substrate or wafer)	USPAT; US-PGPUB	2002/09/22 14:12
-	4	"pulse laser" with ((cutting or cut or dice or dicing or diced) with (substrate or wafer))	USPAT; US-PGPUB	2002/09/22 14:15
-	13	"pulse laser" same ((cutting or cut or dice or dicing or diced) with (substrate or wafer))	USPAT; US-PGPUB	2002/09/22 14:15
-	9	("pulse laser" same ((cutting or cut or dice or dicing or diced) with (substrate or wafer))) not ("pulse laser" with ((cutting or cut or dice or dicing or diced) with (substrate or wafer)))	USPAT; US-PGPUB	2002/09/22 14:19
-	1182	"pulse laser" with "laser beam"	USPAT; US-PGPUB	2002/09/22 14:21
-	112	"ultra short pulse"	USPAT; US-PGPUB	2002/09/22 14:21
-	24	"ultra short pulse laser"	USPAT; US-PGPUB	2002/09/22 14:21
-	18065	adhesive with (back or backside)	USPAT; US-PGPUB	2002/09/25 12:01
-	1847	adhesive with (back or backside) with (wafer or substrate)	USPAT; US-PGPUB	2002/09/25 12:02
-	216407	laser	USPAT; US-PGPUB	2002/09/25 12:02
-	528	short with "pulse laser"	USPAT; US-PGPUB	2002/09/25 12:03
-	1	(adhesive with (back or backside) with (wafer or substrate)) and (short with "pulse laser")	USPAT; US-PGPUB	2002/09/25 12:03
-	514	(adhesive with (back or backside) with (wafer or substrate)) and laser	USPAT; US-PGPUB	2002/09/25 12:04
-	357872	semiconductor or "integrated circuit"	USPAT; US-PGPUB	2002/09/25 12:05
-	298	((adhesive with (back or backside) with (wafer or substrate)) and laser) and (semiconductor or "integrated circuit")	USPAT; US-PGPUB	2002/09/25 12:05